

### 30V N-Channel Enhancement Mode MOSFET

#### Description

The PECN3404VR uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

#### General Features

- ◆  $V_{DS} = 30V$ ,  $I_D = 5A$   
 $R_{DS(ON)}(Typ.) = 25m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(ON)}(Typ.) = 30m\Omega$  @  $V_{GS} = 4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package

#### Application

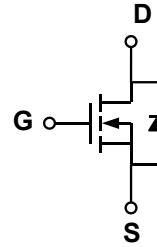
- ◆ PWM applications
- ◆ Load switch

#### Package

- ◆ SOT-23

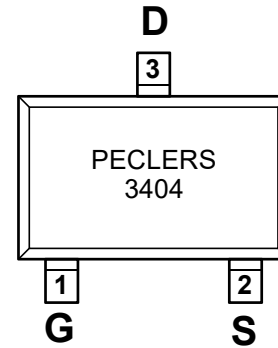


#### Schematic diagram



#### Marking and pin assignment

SOT-23  
(TOP VIEW)



#### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
PECN3404VR	-55°C to +150°C	SOT-23	3000

#### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	30	V
Gate-source voltage	$V_{GS}$	±20	V
Drain current-continuous <sup>a</sup> @Tj=125°C -pulse <sup>b</sup>	$I_D$	5	A
	$I_{DM}$	20	A
Drain-source Diode forward current	$I_S$	5	A
Maximum power dissipation	$P_D$	1.4	W
Operating junction Temperature range	$T_j$	-55—150	°C

parameter	symbol	limit	unit
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Drain-source voltage		$V_{DS}$	-30	V
Gate-source voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_J = 150\text{ }^\circ\text{C}$ )	$T_C = 25\text{ }^\circ\text{C}$	$I_D$	5	A
	$T_C = 70\text{ }^\circ\text{C}$		4	
	$T_A = 25\text{ }^\circ\text{C}$		3.7 <sup>b,c</sup>	
	$T_A = 70\text{ }^\circ\text{C}$		2.9 <sup>b,c</sup>	
Continuous Source-Drain Diode Current		$I_S$	1.4	
			$T_A = 25\text{ }^\circ\text{C}$	
Pulsed Drain Current ( $t = 300\text{ }\mu\text{s}$ )		$I_{DM}$	-12.8	
Maximum power dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	1.7	W
	$T_C = 70\text{ }^\circ\text{C}$		1.1	
	$T_A = 25\text{ }^\circ\text{C}$		1 <sup>b,c</sup>	
	$T_A = 70\text{ }^\circ\text{C}$		0.6 <sup>b,c</sup>	
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55—150	$^\circ\text{C}$

### Thermal Characteristics

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b, d</sup>	$t \leq 5\text{ s}$	$R_{\theta JA}$	100	130	$^\circ\text{C/W}$
Maximum Junction-to-Foot (Drain)	Steady State	$R_{\theta JF}$	60	75	

Notes:

- a.  $T_C = 25\text{ }^\circ\text{C}$ .
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t = 5\text{ s}$ .
- d. Maximum under steady state conditions is  $175\text{ }^\circ\text{C/W}$ .

### Electrical Characteristics ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>OFF Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1	$\mu A$
Gate-body leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
<b>ON Characteristics</b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.8	1.35	1.9	V
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 5A$	-	25	30	m $\Omega$
		$V_{GS} = 4.5V, I_D = 4A$	-	30	36	
Forward transconductance	$g_{fs}$	$V_{DS} = 5V, I_D = 5A$	-	15	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V$ $f = 1.0\text{ MHz}$	-	255	-	pF
Output capacitance	$C_{oss}$		-	45	-	

Reverse transfer capacitance	$C_{RSS}$		-	35	-	
<b>Switching Characteristics</b>						
Turn-on delay time	$t_{D(ON)}$	$V_{DS}=15V$ $V_{GS}=10V$ $R_L=2.6\text{ ohm}$ $R_{GEN}=3\text{ohm}$	-	4.5	-	ns
Rise time	$t_r$		-	2.5	-	
Turn-off delay time	$t_{D(OFF)}$		-	14.5	-	
Fall time	$t_f$		-	3.5	-	
Total gate charge	$Q_g$	$V_{DS}=15V, I_D=5.8A$ $V_{GS}=10V$	-	5.2	-	nC
Gate-source charge	$Q_{gs}$		-	0.85	-	
Gate-drain charge	$Q_{gd}$		-	1.3	-	
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Diode forward voltage	$V_{SD}$	$V_{GS}=0V, I_s=1A$	-	0.76	1.16	V

### Typical Performance Characteristics

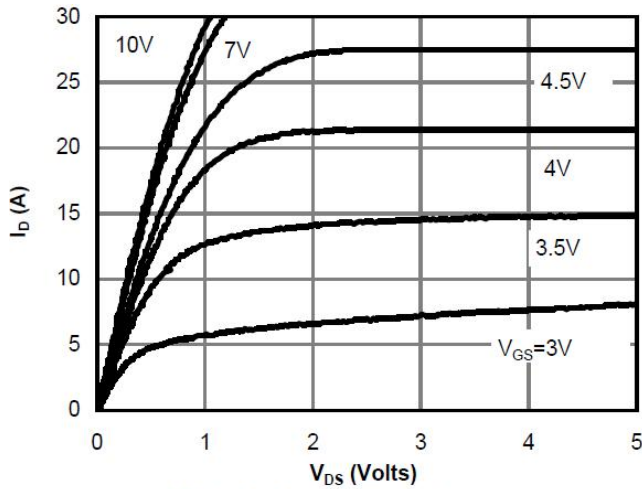


Figure 1: On-Region Characteristics

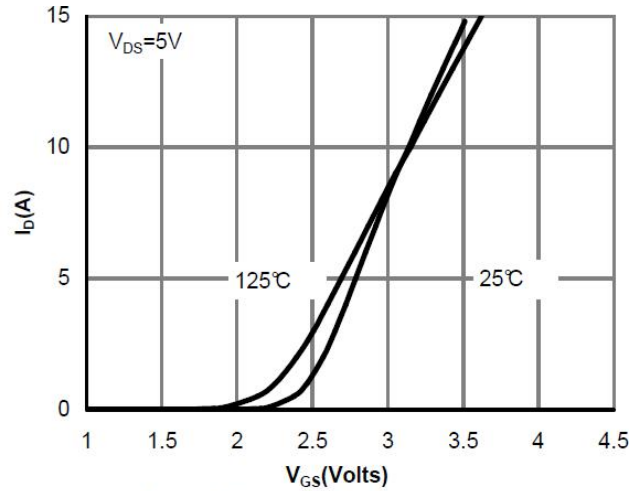


Figure 2: Transfer Characteristics

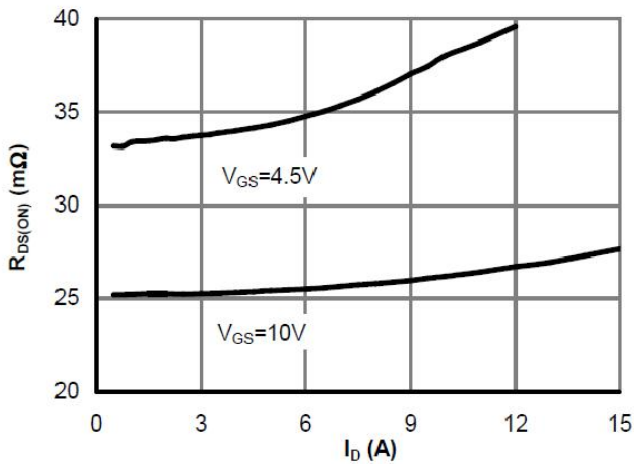


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

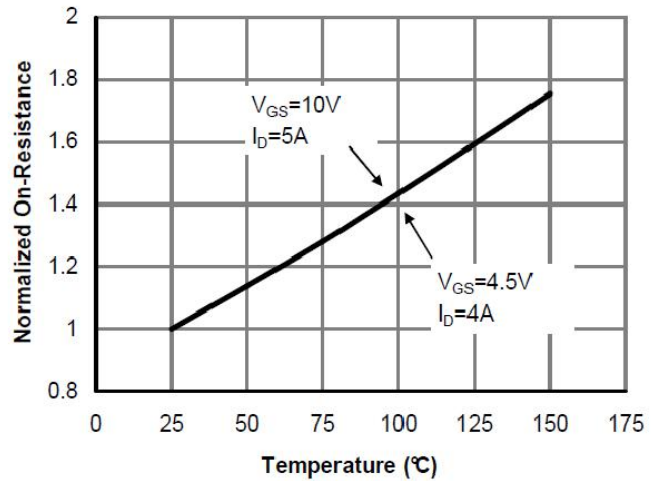


Figure 4: On-Resistance vs. Junction Temperature

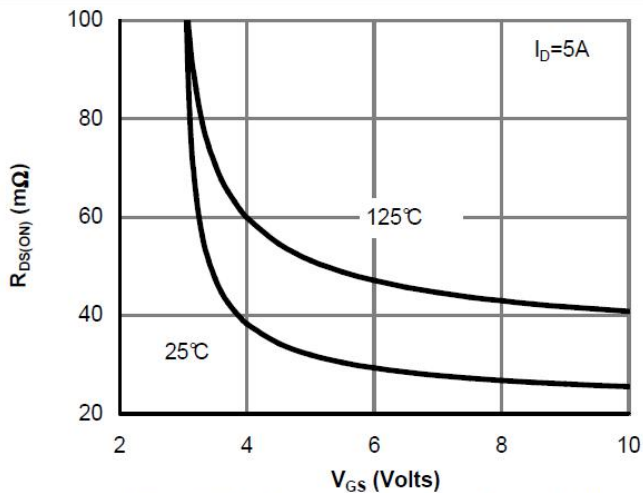


Figure 5: On-Resistance vs. Gate-Source Voltage

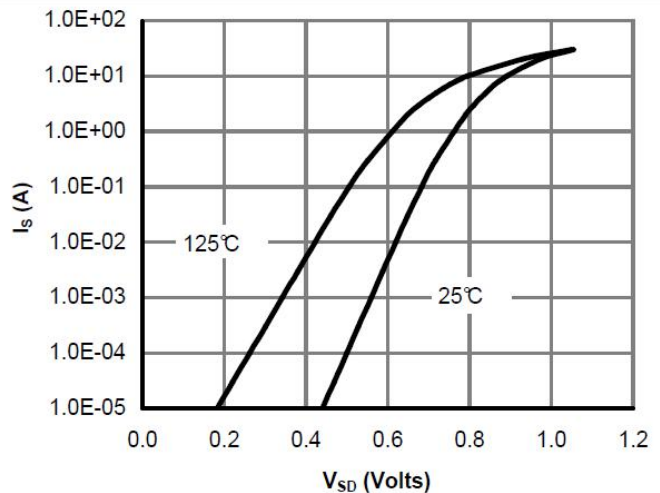


Figure 6: Body-Diode Characteristics

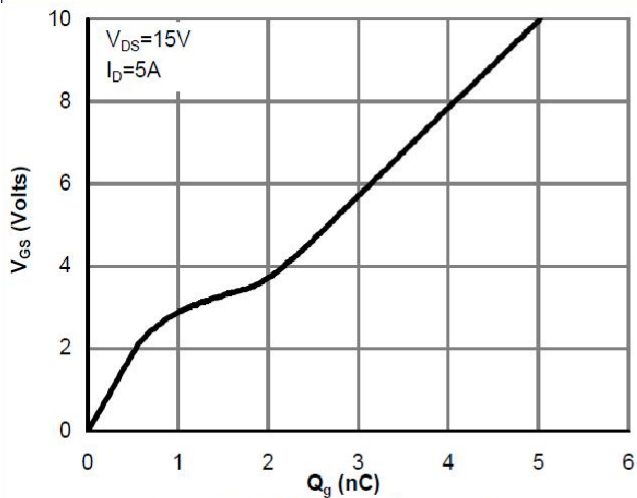


Figure 7: Gate-Charge Characteristics

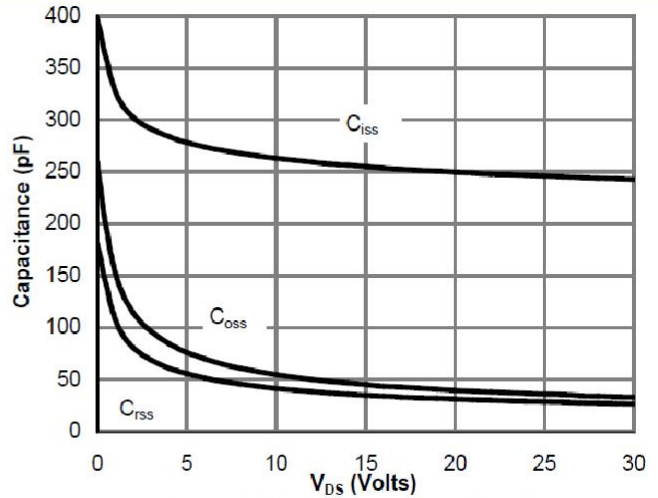


Figure 8: Capacitance Characteristics

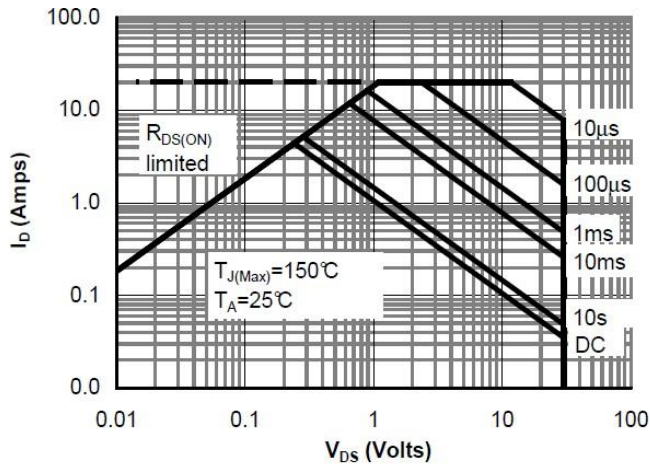


Figure 10: Maximum Forward Biased Safe Operating Area

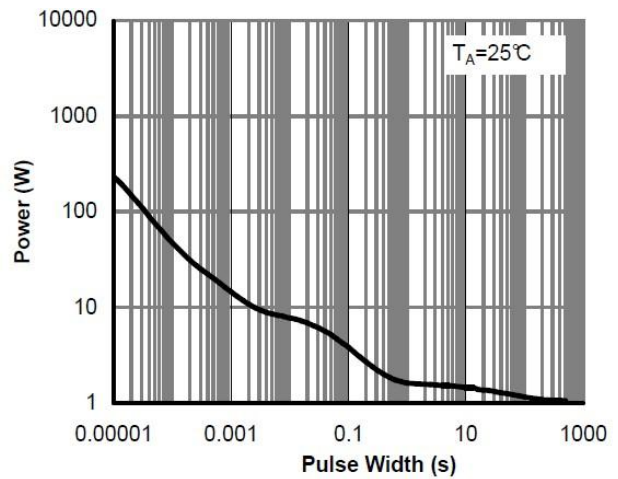


Figure 11: Single Pulse Power Rating Junction-to-Ambient

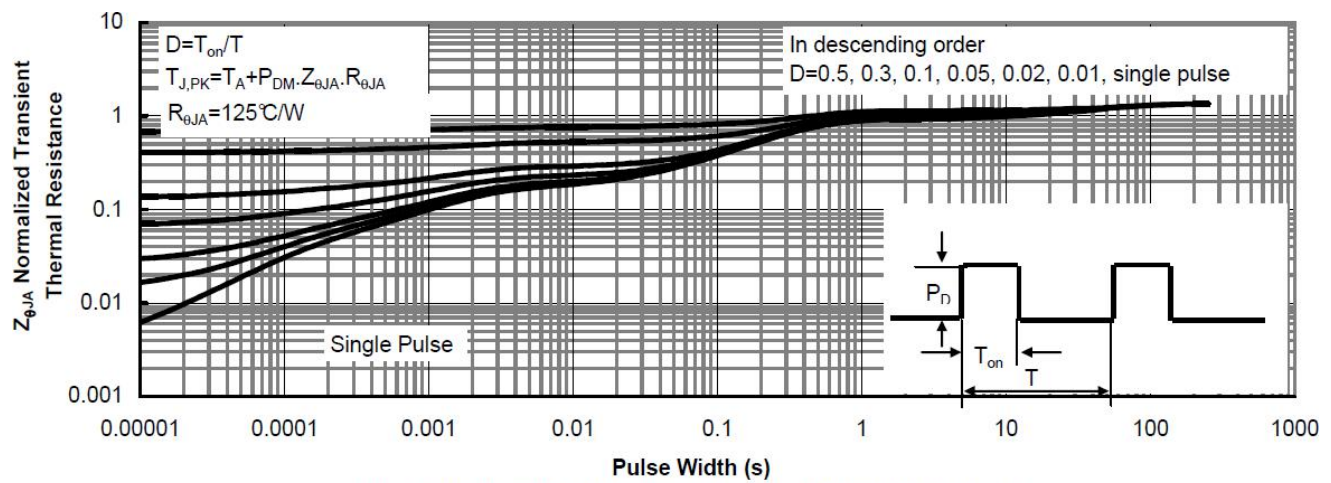
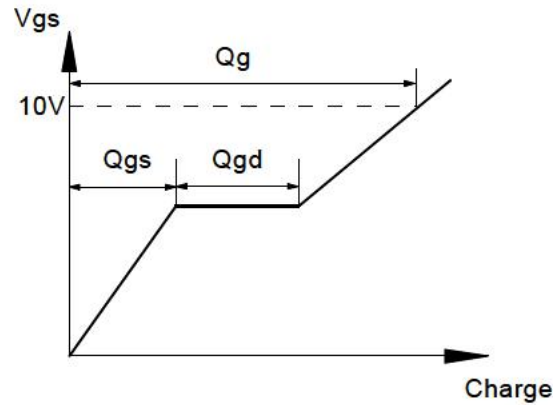
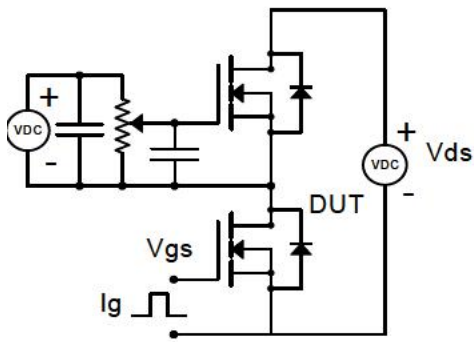


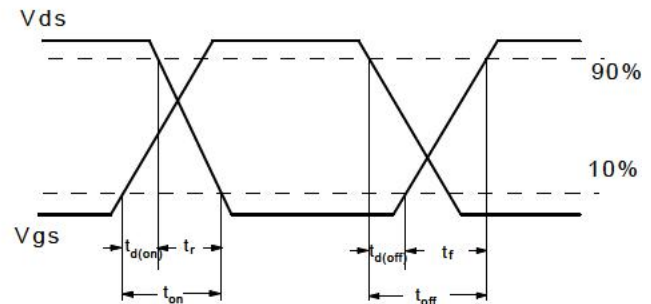
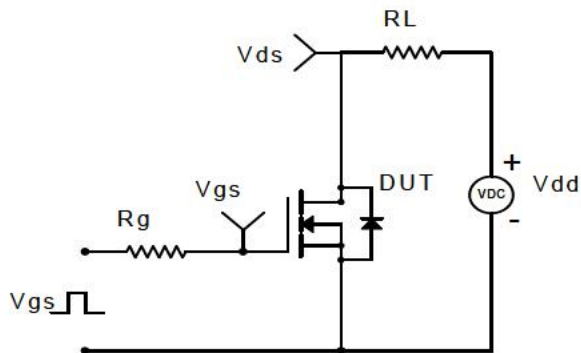
Figure 12: Normalized Maximum Transient Thermal Impedance

## Gate Charge Test Circuit & Waveform

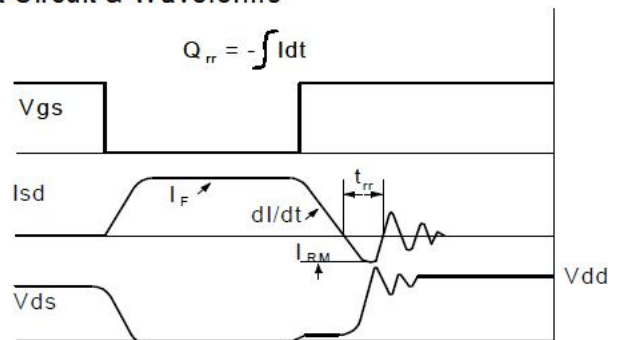
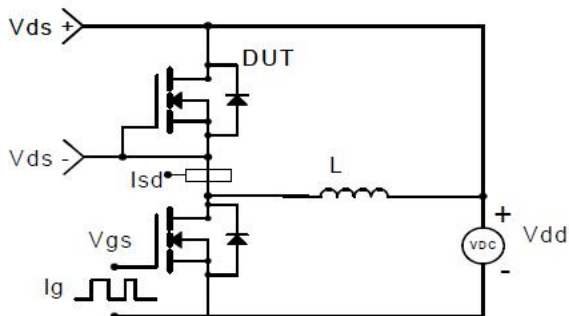


## Resistive Switching Test Circuit & Waveforms

### Resistive Switching Test Circuit & Waveforms

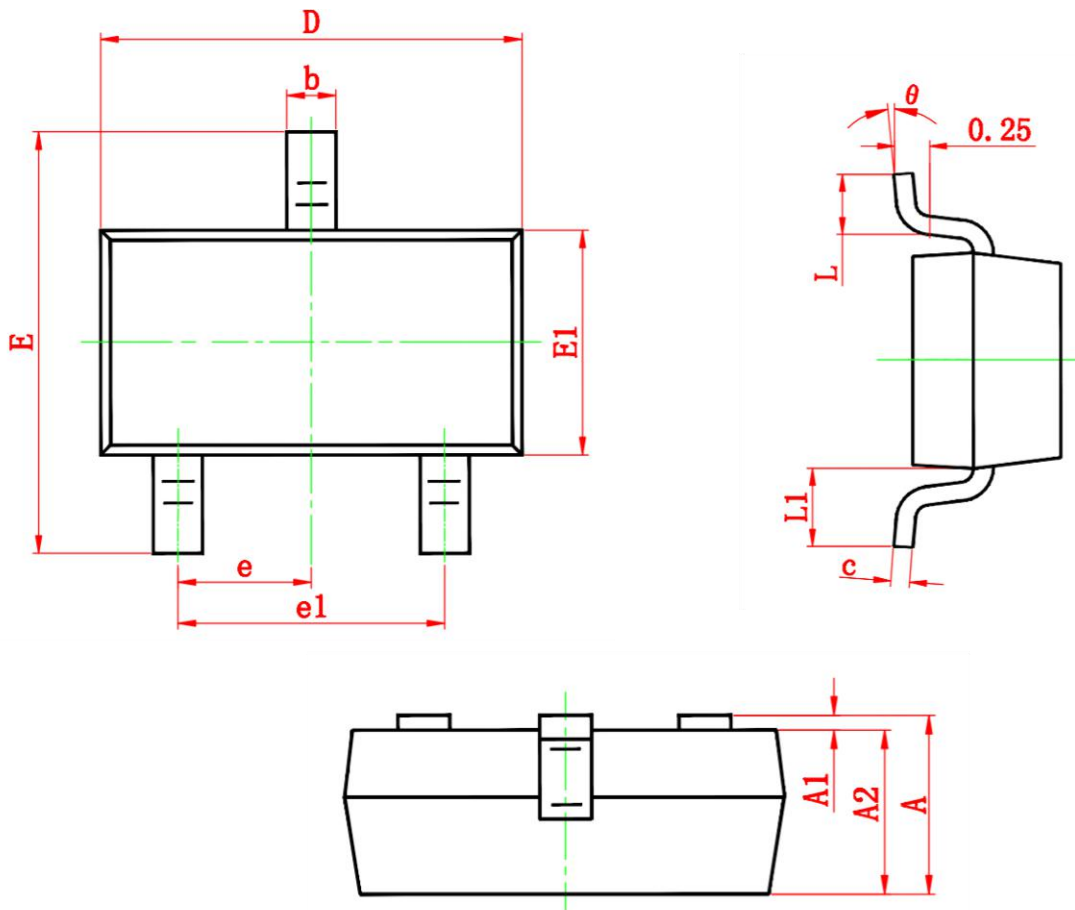


## Diode Recovery Test Circuit & Waveforms



### Package Information

- SOT-23



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	2.250	2.550	0.089	0.100
E1	1.200	1.400	0.047	0.055
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.300	0.500	0.012	0.020
L1	0.550 REF.		0.022 REF.	
θ	0°	8°	0°	8°